

MATERIAL DECLARATION SHEET



Material Number	CD2010 Series			
Product Line	Schottky Rectifier Diodes			
Compliance Date	January 1, 2005			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Others	12	Continuous filament glass fibers	65997-17-3	43	25.8	60.00
				Copper	7440-50-8	14	8.4	
				Non-Hazardous cured resin	Proprietary	43	25.8	
2	Epoxy	Plastic	5.36	Silicon Dioxide	7631-86-9	55	14.74	26.80
				Bisphenol type epoxy	9003-36-5	45	12.06	
3	Solder Cream	Metal	0.94	Lead *2	7439-92-1	88	4.136	4.70
				Tin	7440-31-5	10	0.47	
				Silver	7440-22-4	2	0.094	
4	Dice	Others	1.30	Silicon	7440-21-3	90.46	5.8799	6.50
				Silver	7440-22-4	8.5	0.5525	
				Nickel	7440-02-0	0.67	0.04355	
				Titanium	7440-32-6	0.27	0.01755	
				Arsenic	7440-38-2	0.09	0.00585	
Phosphorus	7723-14-0	0.01	0.00065					
5	Terminal Plating	Metal	0.4	Tin	7440-31-5	100	2	2.00
			Total weight	20				

This Document was updated on: 2015/05/05

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Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
2. * : Excepted for RoHS 7(a)-Lead in high melting temperature type solders (i.e. lead- based alloys containing 85% by weight or more lead) ;